



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC3XXN10NM6	Issued	09. February 2022
MA#	MA005428245		
Package	PG-TDSON-8-25	Weight*	113.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.318	0.28	0.28	2790	2790
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		429	
	non noble metal	copper	7440-50-8	48.769	42.81	42.86	428038	428596
wire	noble metal	gold	7440-57-5	0.048	0.04	0.04	421	421
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		747	
	plastics	epoxy resin	-	6.720	5.90		58982	
	inorganic material	silicondioxide	60676-86-0	35.727	31.36	37.33	313573	373302
leadfinish	non noble metal	tin	7440-31-5	1.392	1.22	1.22	12213	12213
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1701	1701
solder	non noble metal	tin	7440-31-5	0.010	0.01		86	
	noble metal	silver	7440-22-4	0.012	0.01		108	
	non noble metal	lead	7439-92-1	0.469	0.41	0.43	4115	4309
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	17.131	15.04	15.06	150359	150555
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.61	2.61	26079	26113
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com